

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

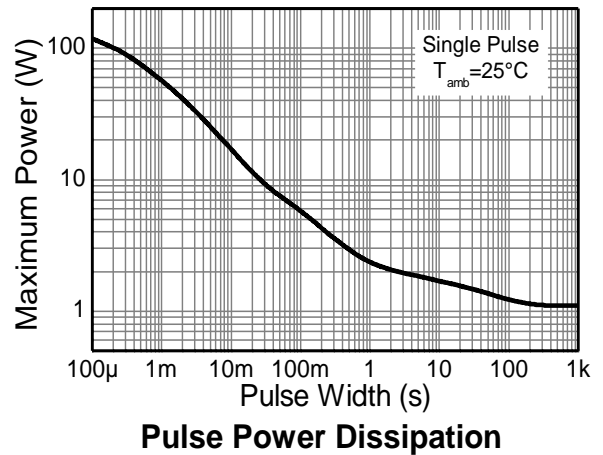
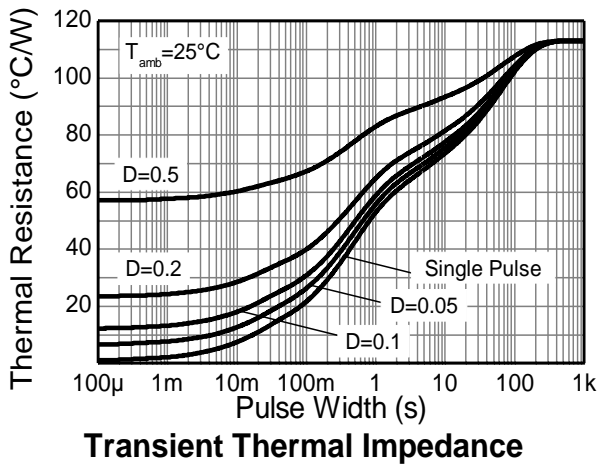
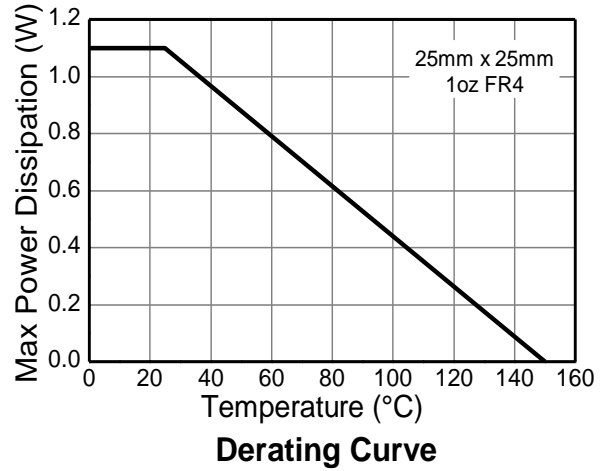
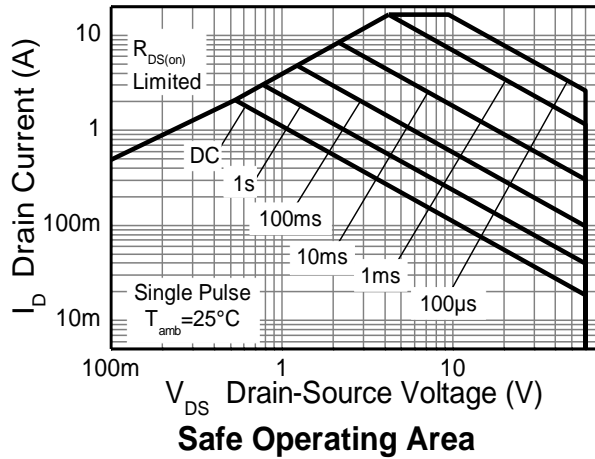
Characteristic			Symbol	Value	Unit	
Drain-Source Voltage			V _{DSS}	60	V	
Gate-Source Voltage			V _{GS}	±20	V	
Continuous Drain Current	V _{GS} = 10V	(Note 7)	I _D	3.5	A	
		T _A = +70°C (Note 7)		2.8		
		(Note 6)		2.8		
Pulsed Drain Current	V _{GS} = 10V	(Note 8)	I _{DM}	16	A	
Continuous Source Current (Body diode)			(Note 7)	I _S	2.6	A
Pulsed Source Current (Body diode)			(Note 8)	I _{SM}	16	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Note 6)	P _D	1.1	W mW/°C
			8.8	
	(Note 7)		1.7 13.6	
Thermal Resistance, Junction to Ambient	(Note 6)	R _{θJA}	113	°C/W
	(Note 7)		73	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

- Notes:
6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 7. Same as Note 6, except the device is measured at t ≤ 10 seconds.
 8. Same as Note 6, except the device is pulsed with D = 0.02 and pulse width 300µs. The pulse current is limited by the maximum junction temperature.

Thermal Characteristics

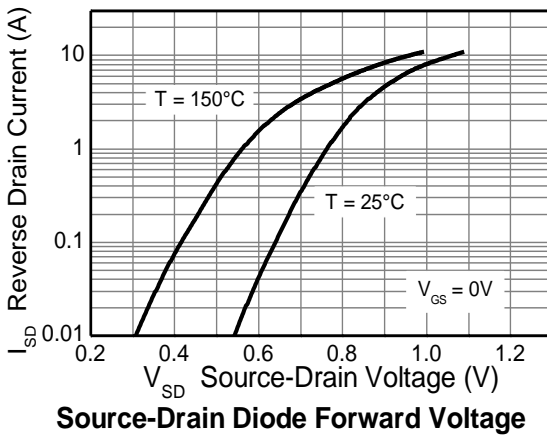
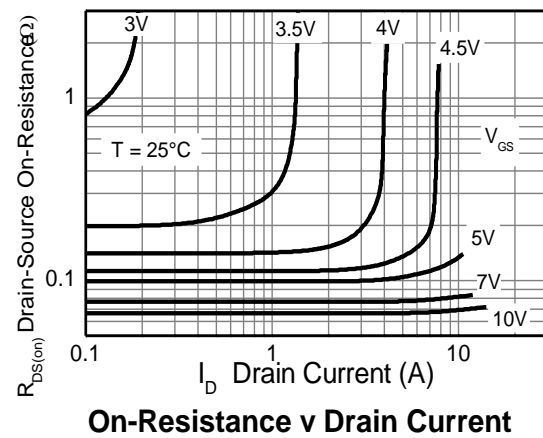
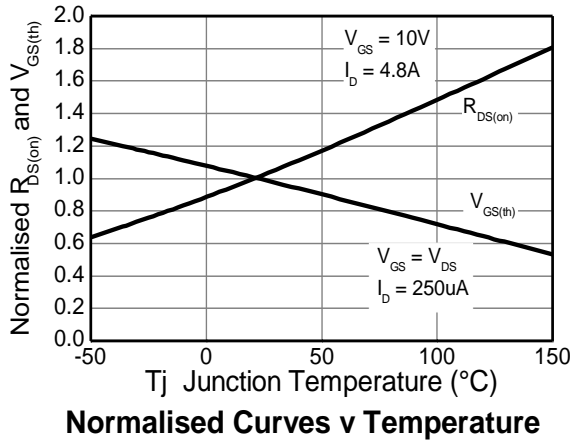
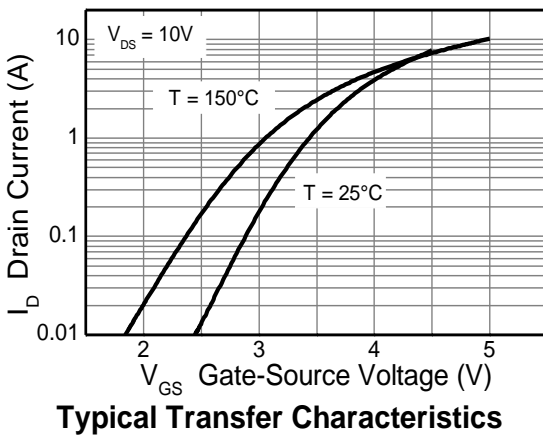
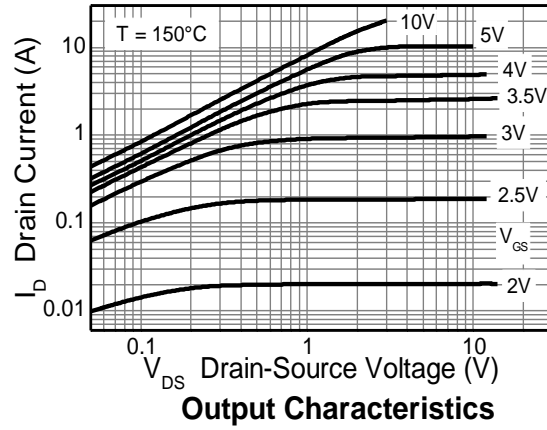
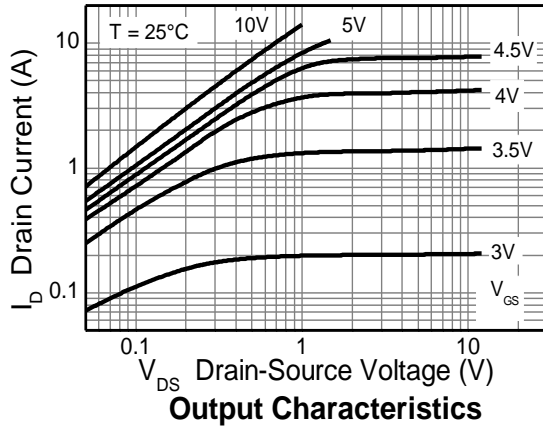


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

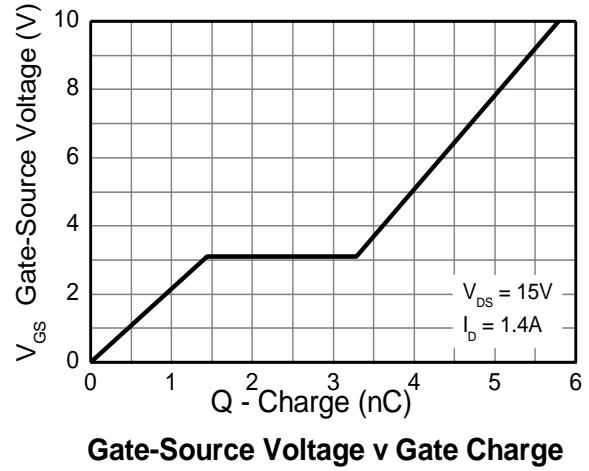
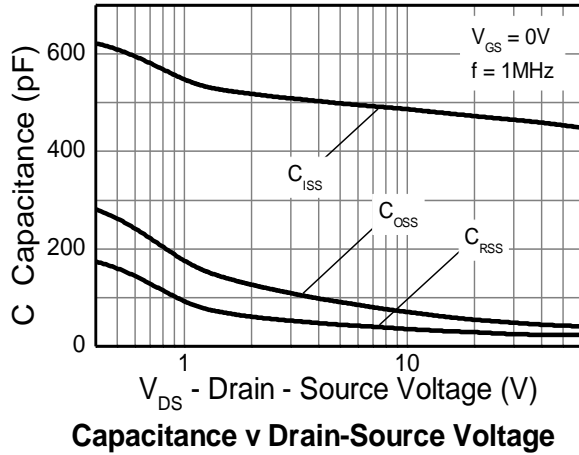
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	60	—	—	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	0.5	μA	V _{DS} = 60V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	1	—	—	V	I _D = 250μA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance (Note 9)	R _{DS(on)}	—	0.067	0.08	Ω	V _{GS} = 10V, I _D = 4.8A
			0.1	0.15		V _{GS} = 4.5V, I _D = 4.2A
Forward Transconductance (Notes 9 & 10)	g _{fs}	—	6.6	—	S	V _{DS} = 15V, I _D = 4.8A
Diode Forward Voltage (Note 9)	V _{SD}	—	0.88	1.2	V	I _S = 4A, V _{GS} = 0V, T _J = +25°C
Reverse Recovery Time (Note 10)	t _{rr}	—	19.2	—	ns	I _F = 1.4A, di/dt = 100A/μs,
Reverse Recovery Charge (Note 10)	Q _{rr}	—	30.3	—	nC	T _J = +25°C
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C _{iss}	—	459	—	pF	V _{DS} = 40V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{oss}	—	44.2	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	24.1	—	pF	
Total Gate Charge (Note 11)	Q _g	—	3.7	—	nC	V _{GS} = 4.5V
Total Gate Charge (Note 11)	Q _g	—	5.8	—	nC	V _{GS} = 10V
Gate-Source Charge (Note 11)	Q _{gs}	—	1.4	—	nC	
Gate-Drain Charge (Note 11)	Q _{gd}	—	1.9	—	nC	
Turn-On Delay Time (Note 11)	t _{D(on)}	—	2.6	—	ns	V _{DD} = 30V, V _{GS} = 10V I _D = 1.5A, R _G ≅ 6Ω
Turn-On Rise Time (Note 11)	t _r	—	2.1	—	ns	
Turn-Off Delay Time (Note 11)	t _{D(off)}	—	12.3	—	ns	
Turn-Off Fall Time (Note 11)	t _f	—	4.6	—	ns	

Notes: 9. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%.
 10. For design aid only, not subject to production testing.
 11. Switching characteristics are independent of operating junction temperatures.

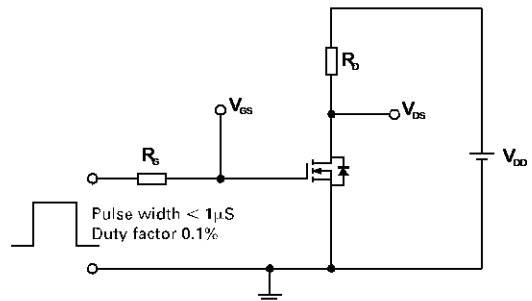
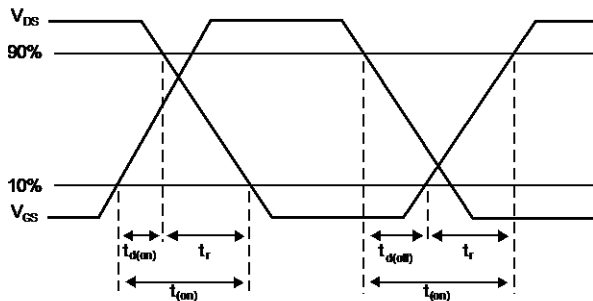
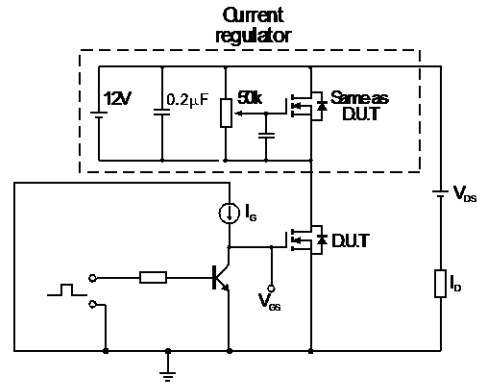
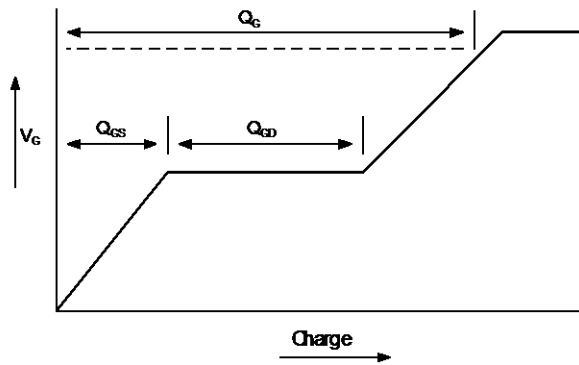
Typical Characteristics



Typical Characteristics (cont.)

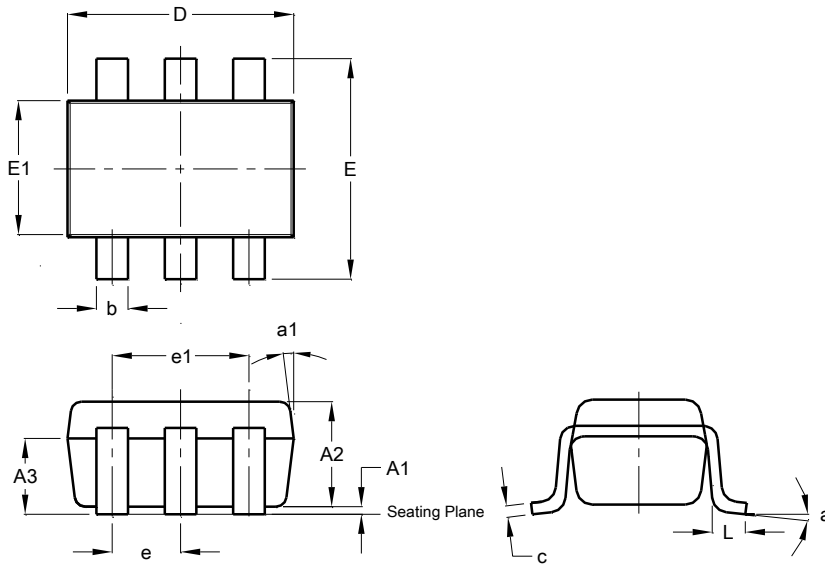


Test Circuits



Package Outline Dimensions

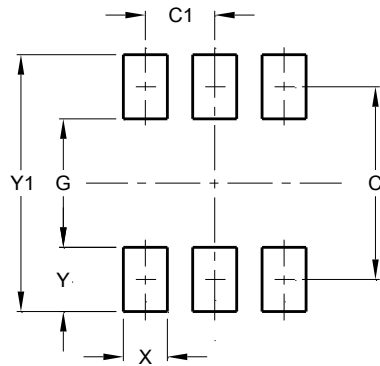
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT26			
Dim	Min	Max	Typ
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
c	0.10	0.20	0.15
D	2.90	3.10	3.00
e	-	-	0.95
e1	-	-	1.90
E	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
a	-	-	8°
a1	-	-	7°
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20

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